

# LOW SKEW, DUAL, 1-TO-3, DIFFERENTIAL-TO-2.5V, 3.3V, 5V LVPECL/ECL FANOUT BUFFER

**ICS853013**

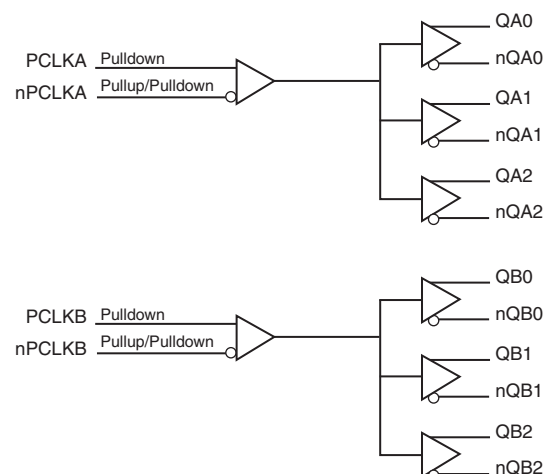
## General Description

The ICS853013 is a low skew, high performance dual 1-to-3 Differential-to-2.5V/3.3V/5V LVPECL/ECL Fanout Buffer and a member of the HiperClocks™ family of High Performance Clock Solutions from IDT. The ICS853013 operates with a positive or negative power supply at 2.5V, 3.3V, or 5V. Guaranteed output and part-to-part skew characteristics make the ICS853013 ideal for those clock distribution applications demanding well defined performance and repeatability.

## Features

- Two differential LVPECL/ECL bank outputs
- Two differential LVPECL clock input pairs
- PCLKx, nPCLKx pairs can accept the following differential input levels: LVPECL, LVDS, CML, SSTL
- Output frequency: >2GHz (typical)
- Translates any single-ended input signal to LVPECL levels with resistor bias on nPCLKx input
- Output skew: 40ps (maximum)
- Part-to-part skew: 250ps (maximum)
- Propagation delay: 5780ps (maximum)
- Additive phase jitter, RMS: 0.03ps (typical)
- LVPECL mode operating voltage supply range:  $V_{CC} = 2.375V$  to  $5.25V$ ,  $V_{EE} = 0V$
- ECL mode operating voltage supply range:  $V_{CC} = 0V$ ,  $V_{EE} = -5.25V$  to  $-2.375V$
- $-40^{\circ}C$  to  $85^{\circ}C$  ambient operating temperature
- Available in both standard (RoHS 5) and lead-free (RoHS 6) packages

## Block Diagram



## Pin Assignment

nQA0	1	20	QA1
QA0	2	19	nQA1
Vcc	3	18	QA2
PCLKA	4	17	nQA2
nPCLKA	5	16	Vcc
PCLKB	6	15	QB2
nPCLKB	7	14	nQB2
Vcc	8	13	QB1
nQB0	9	12	nQB1
QB0	10	11	VEE

**ICS853013**

**20-Lead SOIC**

**7.5mm x 12.8mm x 2.3mm package body**

**M Package**

**Top View**

**Table 1. Pin Descriptions**

Number	Name	Type		Description
1, 2	nQA0, QA0	Output		Differential output pair. LVPECL interface levels.
3, 8, 16	V <sub>CC</sub>	Power		Power supply pins.
4	PCLKA	Input	Pulldown	Non-inverting differential LVPECL clock input.
5	nPCLKA	Input	Pullup/ Pulldown	Inverting differential LVPECL clock input. V <sub>CC</sub> /2 default when left floating.
6	PCLKB	Input	Pulldown	Non-inverting differential LVPECL clock input.
7	nPCLKB	Input	Pullup/ Pulldown	Inverting differential LVPECL clock input. V <sub>CC</sub> /2 default when left floating.
9, 10	nQB0, QB0	Output		Differential output pair. LVPECL interface levels.
11	V <sub>EE</sub>	Power		Negative supply pin.
12, 13	nQB1, QB1	Output		Differential output pair. LVPECL interface levels.
14, 15	nQB2, QB2	Output		Differential output pair. LVPECL interface levels.
17, 18	nQA2, QA2	Output		Differential output pair. LVPECL interface levels.
19, 20	nQA1, QA1	Output		Differential output pair. LVPECL interface levels.

NOTE: Pullup and Pulldown refer to internal input resistors. See Table 2, *Pin Characteristics*, for typical values.

**Table 2. Pin Characteristics**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			75		kΩ
R <sub>VCC/2</sub>	Pullup/Pulldown Resistors			50		kΩ

**Function Table****Table 3. Clock Input Function Table**

Inputs		Outputs		Input to Output Mode	Polarity
PCLKA or PCLKB	nPCLKA or nPCLKB	QA0:Q2, QB0:QB2	nQA0:nQA2, nQB0:nQB2		
0	1	LOW	HIGH	Differential to Differential	Non-Inverting
1	0	HIGH	LOW	Differential to Differential	Non-Inverting
0	Biased; NOTE 1	LOW	HIGH	Single-Ended to Differential	Non-Inverting
1	Biased; NOTE 1	HIGH	LOW	Single-Ended to Differential	Non-Inverting
Biased; NOTE 1	0	HIGH	LOW	Single-Ended to Differential	Inverting
Biased; NOTE 1	1	LOW	HIGH	Single-Ended to Differential	Inverting

NOTE 1: Please refer to the Application Information, *Wiring the Differential Input to Accept Single Ended Levels*.

## Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Supply Voltage, $V_{CC}$	5.5V (LVPECL mode, $V_{EE} = 0V$ )
Negative Supply Voltage, $V_{EE}$	-5.5V (ECL mode, $V_{CC} = 0V$ )
Inputs, $V_I$ (LVPECL mode)	-0.5V to $V_{CC} + 0.5V$
Inputs, $V_I$ (ECL mode)	0.5V to $V_{EE} - 0.5V$
Outputs, $I_O$ Continuous Current Surge Current	50mA 100mA
Operating Temperature Range, $T_A$	-40°C to +85°C
Package Thermal Impedance, $\theta_{JA}$	46.2°C/W (0 lfpm)
Storage Temperature, $T_{STG}$	-65°C to 150°C

## DC Electrical Characteristics

**Table 4A. Power Supply DC Characteristics**,  $V_{CC} = 2.375V$  to  $5.25V$ ;  $V_{EE} = 0V$ ,  $T_A = -40^\circ C$  to  $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{CC}$	Positive Supply Voltage		2.375	3.3	5.25	V
$I_{EE}$	Power Supply Current				60	mA

**Table 4B. LVPECL DC Characteristics**,  $V_{CC} = 3.3V$ ,  $V_{EE} = 0V$ ;  $T_A = -40^\circ C$  to  $85^\circ C$

Symbol	Parameter	-40°C			25°C			80°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OH}$	Output High Voltage; NOTE 1	2.175	2.275	2.38	2.225	2.295	2.37	2.295	2.33	2.365	V
$V_{OL}$	Output Low Voltage; NOTE 1	1.405	1.545	1.68	1.425	1.52	1.615	1.44	1.535	1.63	V
$V_{IH}$	Input High Voltage (Single-ended)	2.075		2.36	2.075		2.36	2.075		2.36	V
$V_{IL}$	Input Low Voltage (Single-ended)	1.43		1.765	1.43		1.765	1.43		1.765	V
$V_{PP}$	Peak-to-Peak Input Voltage	150	800	1200	150	800	1200	150	800	1200	V
$V_{CMR}$	Input High Voltage Common Mode Range; NOTE 2, 3	1.2		3.3	1.2		3.3	1.2		3.3	V
$I_{IH}$	Input High Current	PCLKA, PCLKB nPCLKA, nPCLKB		200			200			200	μA
$I_{IL}$	Input Low Current	PCLKA, PCLKB		-10			-10				μA
		nPCLKA, nPCLKB		-200			-200				μA

Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +0.925V to -0.5V.

NOTE 1: Outputs terminated with 50Ω to  $V_{CC} - 2V$ .

NOTE 2: Common mode voltage is defined as  $V_{IH}$ .

NOTE 3: For single-ended applications, the maximum input voltage for PCLKx, nPCLKx is  $V_{CC} + 0.3V$ .

Table 4C. LVPECL DC Characteristics,  $V_{CC} = 2.5V$ ,  $V_{EE} = 0V$ ;  $T_A = -40^{\circ}C$  to  $85^{\circ}C$ 

Symbol	Parameter	-40°C			25°C			80°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OH}$	Output High Voltage; NOTE 1	1.375	1.475	1.58	1.425	1.495	1.57	1.495	1.53	1.565	V
$V_{OL}$	Output Low Voltage; NOTE 1	0.605	0.745	0.88	0.625	0.72	0.815	0.64	0.735	0.83	V
$V_{IH}$	Input High Voltage (Single-ended)	1.275		1.56	1.275		1.56	1.275		-0.8	V
$V_{IL}$	Input Low Voltage (Single-ended)	0.63		0.965	0.63		0.965	0.63		0.965	V
$V_{PP}$	Peak-to-Peak Input Voltage	150	800	1200	150	800	1200	150	800	1200	V
$V_{CMR}$	Input High Voltage Common Mode Range; NOTE 2, 3	1.2		2.5	1.2		2.5	1.2		2.5	V
$I_{IH}$	Input High Current	PCLKA, PCLKB nPCLKA, nPCLKB		200			200			200	$\mu A$
$I_{IL}$	Input Low Current	PCLKA, PCLKB		-10	-10			-10			$\mu A$
		nPCLKA, nPCLKB		-200	-200			-200			$\mu A$

Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +0.925V to -0.5V.

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{CC} - 2V$ .

NOTE 2: Common mode voltage is defined as  $V_{IH}$ .

NOTE 3: For single-ended applications, the maximum input voltage for PCLKx, nPCLKx is  $V_{CC} + 0.3V$ .

Table 4D. LVPECL DC Characteristics,  $V_{CC} = 5V$ ,  $V_{EE} = 0V$ ;  $T_A = -40^{\circ}C$  to  $85^{\circ}C$ 

Symbol	Parameter	-40°C			25°C			80°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OH}$	Output High Voltage; NOTE 1	-1.125	-1.025	-0.92	-1.075	-1.005	-0.93	-1.005	-0.97	-0.935	V
$V_{OL}$	Output Low Voltage; NOTE 1	-1.895	-1.755	-1.62	-1.875	-1.78	-1.685	-1.86	-1.76 5	-1.67	V
$V_{IH}$	Input High Voltage (Single-ended)	-1.225		-0.94	-1.225		-0.94	-1.225		-0.94	V
$V_{IL}$	Input Low Voltage (Single-ended)	-1.87		-1.535	-1.87		-1.535	-1.87		-1.535	V
$V_{PP}$	Peak-to-Peak Input Voltage	150	800	1200	150	800	1200	150	800	1200	V
$V_{CMR}$	Input High Voltage Common Mode Range; NOTE 2, 3	$V_{EE}+1.2$		0	$V_{EE}+1.2$		0	$V_{EE}+1.2$		0	V
$I_{IH}$	Input High Current	PCLKA, PCLKB nPCLKA, nPCLKB		200			200			200	$\mu A$
$I_{IL}$	Input Low Current	PCLKA, PCLKB		-10	-10			-10			$\mu A$
		nPCLKA, nPCLKB		-200	-200			-200			$\mu A$

Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +0.925V to -0.5V.

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{CC} - 2V$ .

NOTE 2: Common mode voltage is defined as  $V_{IH}$ .

NOTE 3: For single-ended applications, the maximum input voltage for PCLKx, nPCLKx is  $V_{CC} + 0.3V$ .

**Table 4E. ECL DC Characteristics**,  $V_{CC} = 0V$ ,  $V_{EE} = -5.25V$  to  $-2.375V$ ;  $T_A = -40^{\circ}C$  to  $85^{\circ}C$ 

Symbol	Parameter	-40°C			25°C			80°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OH}$	Output High Voltage; NOTE 1	-1.125	-1.025	-0.92	-1.075	-1.005	-0.93	-1.005	-0.97	-0.935	V
$V_{OL}$	Output Low Voltage; NOTE 1	-1.895	-1.755	-1.62	-1.875	-1.78	-1.685	-1.86	-1.765	-1.67	V
$V_{IH}$	Input High Voltage (Single-ended)	-1.225		-0.94	-1.225		-0.94	-1.225		-0.94	V
$V_{IL}$	Input Low Voltage (Single-ended)	-1.87		-1.535	-1.87		-1.535	-1.87		-1.535	V
$V_{PP}$	Peak-to-Peak Input Voltage	150	800	1200	150	800	1200	150	800	1200	V
$V_{CMR}$	Input High Voltage Common Mode Range; NOTE 2, 3	$V_{EE}+1.2$		0	$V_{EE}+1.2$		0	$V_{EE}+1.2$		0	V
$I_{IH}$	Input High Current	PCLKA, PCLKB nPCLKA, nPCLKB		200			200			200	$\mu A$
$I_{IL}$	Input Low Current	PCLKA, PCLKB		-10			-10			-10	$\mu A$
		nPCLKA, nPCLKB		-200			-200			-200	$\mu A$

Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary  $+0.925V$  to  $-0.5V$ .

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{CC} - 2V$ .

NOTE 2: Common mode voltage is defined as  $V_{IH}$ .

NOTE 3: For single-ended applications, the maximum input voltage for PCLKx, nPCLKx is  $V_{CC} + 0.3V$

## AC Electrical Characteristics

**Table 5. AC Characteristics**,  $V_{CC} = 0V$ ,  $V_{EE} = -5.25V$  to  $-2.375V$  or;  $V_{CC} = 2.375V$  to  $5.25V$ ,  $V_{EE} = 0V$ ;  $T_A = -40^{\circ}C$  to  $85^{\circ}C$ 

Symbol	Parameter		-40°C			25°C			80°C			Units
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f <sub>MAX</sub>	Output Frequency			>2			>2			>2		GHz
t <sub>P<sub>LH</sub></sub>	Propagation Delay; Low-to-High; NOTE 1		300	410	510	330	425	520	360	465	570	ps
t <sub>P<sub>HL</sub></sub>	Propagation Delay; High-to-Low; NOTE 1		300	410	510	330	425	520	360	465	570	ps
t <sub>sk(o)</sub>	Output Skew; NOTE 2, 4				40			40			40	ps
t <sub>sk(odc)</sub>	Output Duty Cycle Skew				40			40			40	ps
t <sub>sk(pp)</sub>	Part-to-Part Skew; NOTE 3, 4				250			250			250	ps
f <sub>jit</sub>	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter Section			0.03			0.03			0.03		ps
t <sub>R</sub> / t <sub>F</sub>	Output Rise/Fall Time	20% to 80%	120	180	250	120	180	250	120	180	250	ps

All parameters are measured at  $f \leq 1GHz$ , unless otherwise noted.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at the output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions.

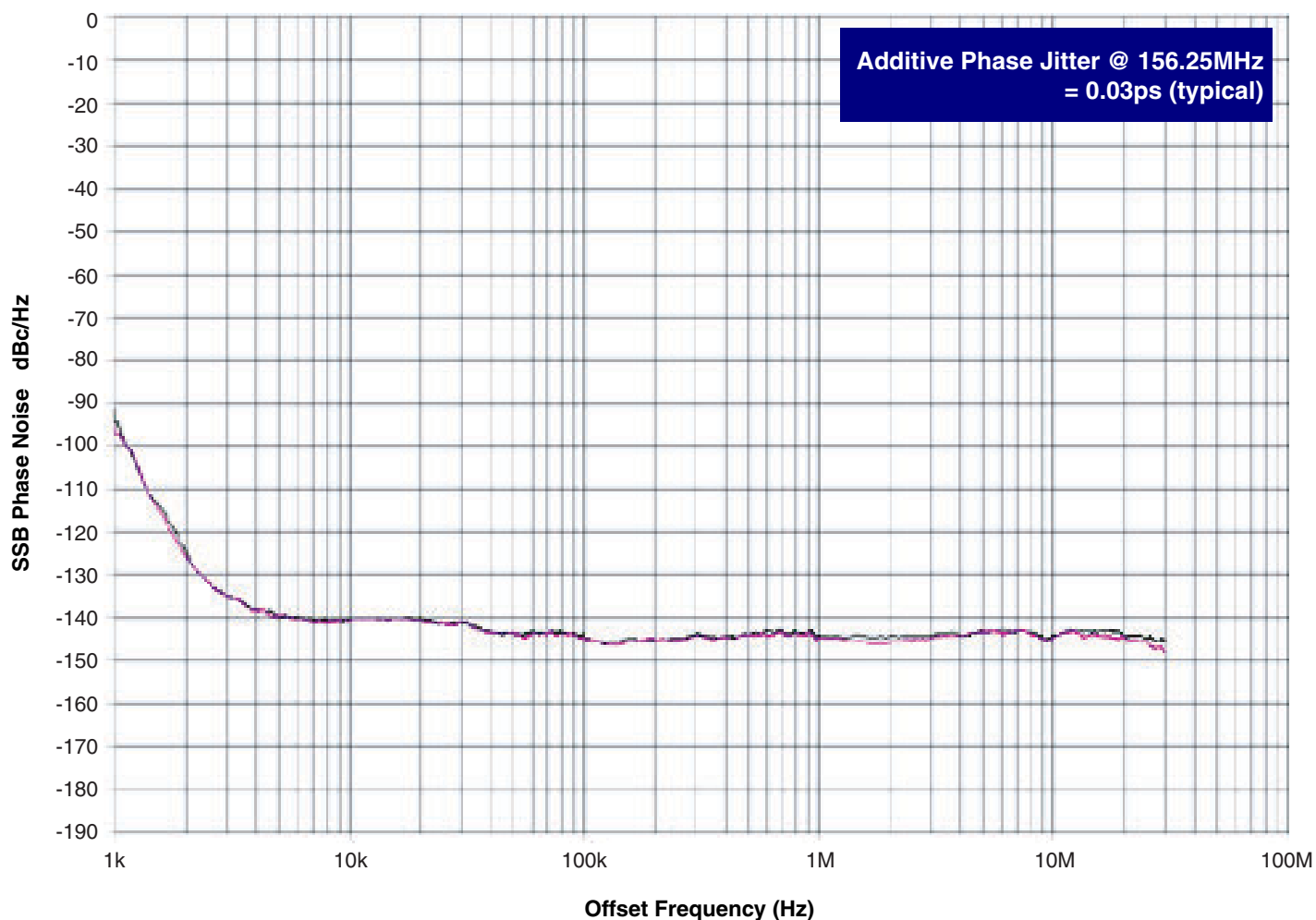
Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.

## Additive Phase Jitter

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the **dBc Phase Noise**. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power in the 1Hz band

to the power in the fundamental. When the required offset is specified, the phase noise is called a **dBc** value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



As with most timing specifications, phase noise measurements has issues relating to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The device meets the noise floor

of what is shown, but can actually be lower. The phase noise is dependent on the input source and measurement equipment.

The diagram shows an LVPECL driver circuit. The driver is represented by a triangle with 'LVPECL' inside. Its top input is connected to a 2V supply labeled  $V_{CC}$ . Its bottom input is connected to a supply labeled  $V_{EE}$  with a range of -3.25V to -0.375V. The driver has two outputs: the top output is labeled 'Qx' and the bottom output is labeled 'nQx'. Each output is connected to a thick black line representing a transmission line with impedance  $Z = 50\Omega$ . The 'Qx' line is connected to a 50Ω resistor to ground, and the 'nQx' line is connected to a 50Ω resistor to ground. Both output lines are also connected to a box labeled 'SCOPE', which represents a scope input with 50Ω termination to ground.

Timing diagram for a crossbar array showing the relationship between  $nPCLKx$  and  $PCLKx$  signals. The signals are periodic with period  $V_{PP}$ . The high level is  $V_{CM}$  and the low level is  $V_{EE}$ . The signals are labeled "Cross Points" at the intersections.

The diagram illustrates a two-stage pipeline with two parts. Part 1 shows a data hazard where the output of the first stage (nQx) is used as input to the second stage (Qx). Part 2 shows a pipeline flush where the output of the first stage (nQy) is used as input to the second stage (Qy). The time interval between the start of the first stage and the start of the second stage is labeled  $tsk(pp)$ .

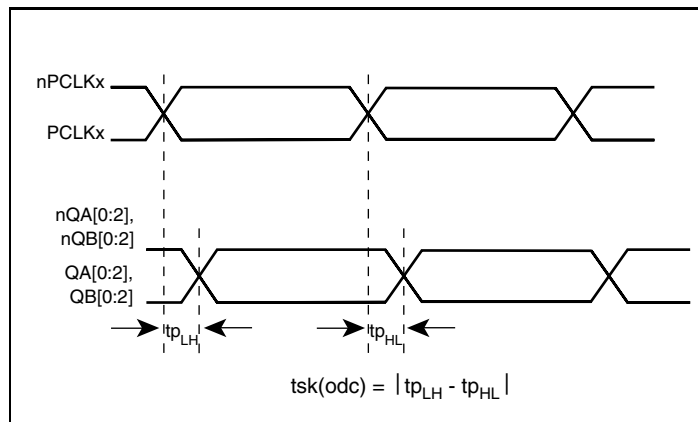
The diagram shows four signal traces:  $nQ_x$ ,  $Q_x$ ,  $nQ_y$ , and  $Q_y$ . The top two traces ( $nQ_x$  and  $Q_x$ ) show a carry signal that propagates from right to left. The bottom two traces ( $nQ_y$  and  $Q_y$ ) show the data signals. A vertical dashed line marks the start of the carry propagation, and a horizontal double-headed arrow labeled  $t_{sk(o)}$  indicates the time interval between the start of the carry and the completion of the data signal transition.

The diagram shows a clock signal waveform. The signal transitions from a low level to a high level and back to a low level. The rise time,  $t_R$ , is the time interval from the 20% voltage level to the 80% voltage level during the rising edge. The fall time,  $t_F$ , is the time interval from the 80% voltage level to the 20% voltage level during the falling edge. The total voltage swing is labeled  $V_{SWING}$ .

The diagram illustrates the timing relationship between the PCLx and QA/QB signals. The top section shows the clock signals nPCLKx and PCLKx. The bottom section shows the data signals nQA[0:2], nQB[0:2] and QA[0:2], QB[0:2]. The signals are shown as digital waveforms with setup and hold times indicated by arrows and labels  $t_{tp\_LH}$  and  $t_{tp\_HL}$ .

IDT™ / ICS™ 2.5V, 3.3V, 5V LVPECL/ECL FANOUT BUFFER

## Parameter Measurement Information, continued



Output Duty Cycle Skew

## Application Information

### Wiring the Differential Input to Accept Single-ended LVCMOS Levels

Figure 1 shows an example of the differential input that can be wired to accept single-ended LVCMOS levels. The reference voltage level  $V_{BB}$  generated from the device is connected to the

negative input. The C1 capacitor should be located as close as possible to the input pin.

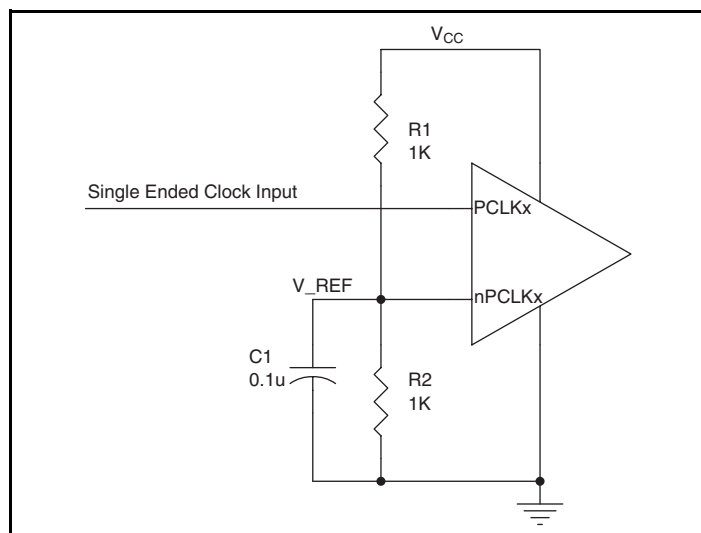


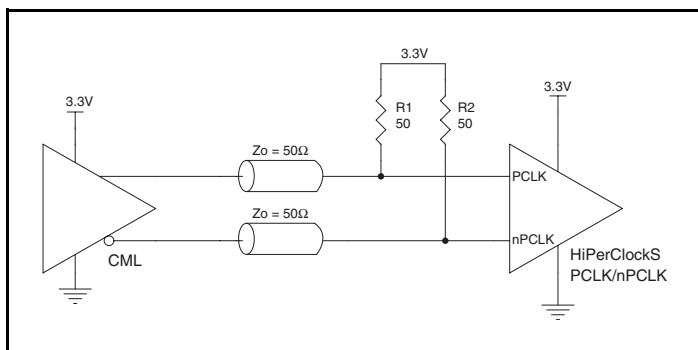
Figure 1. Single-Ended LVCMOS Signal Driving Differential Input



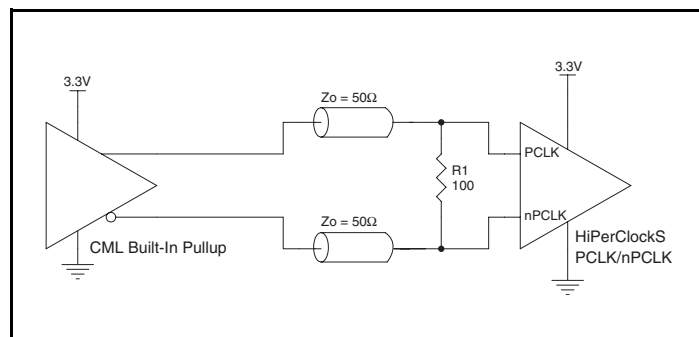
## LVPECL Clock Input Interface

The PCLK/nPCLK accepts LVPECL, LVDS, CML, SSTL and other differential signals. Both  $V_{\text{SWING}}$  and  $V_{\text{OH}}$  must meet the  $V_{\text{PP}}$  and  $V_{\text{CMR}}$  input requirements. Figures 2A to 2F show interface examples for the HiPerClockS PCLK/nPCLK input driven by the

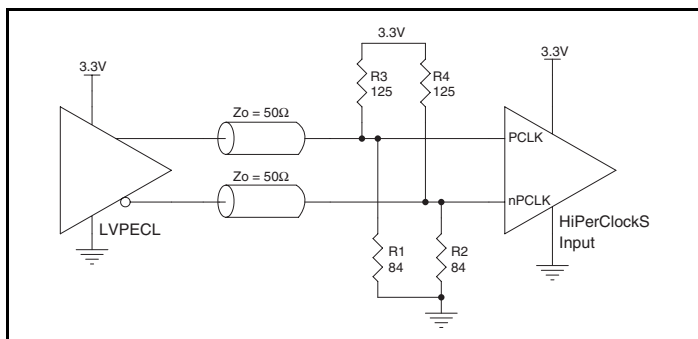
most common driver types. The input interfaces suggested here are examples only. If the driver is from another vendor, use their termination recommendation. Please consult with the vendor of the driver component to confirm the driver termination requirements.



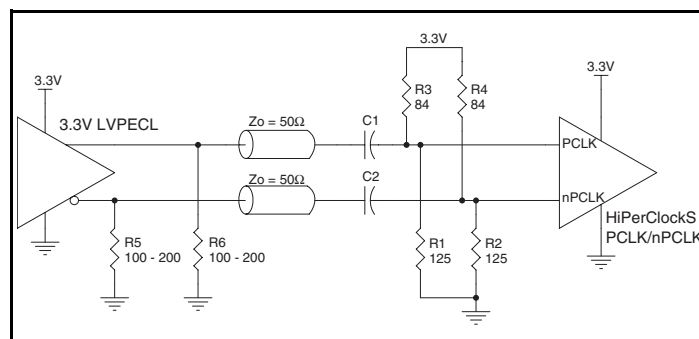
**Figure 2A. HiPerClockS PCLK/nPCLK Input Driven by an Open Collector CML Driver**



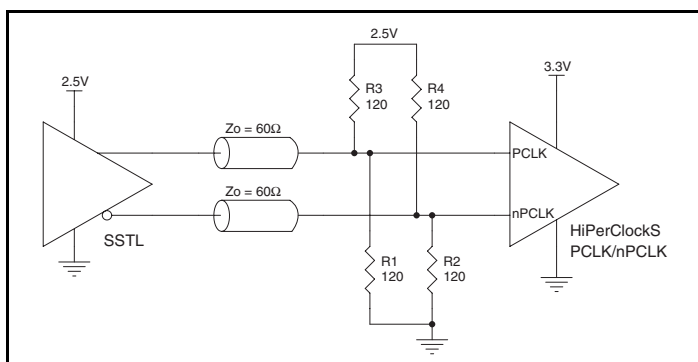
**Figure 2B. HiPerClockS PCLK/nPCLK Input Driven by a Built-In Pullup CML Driver**



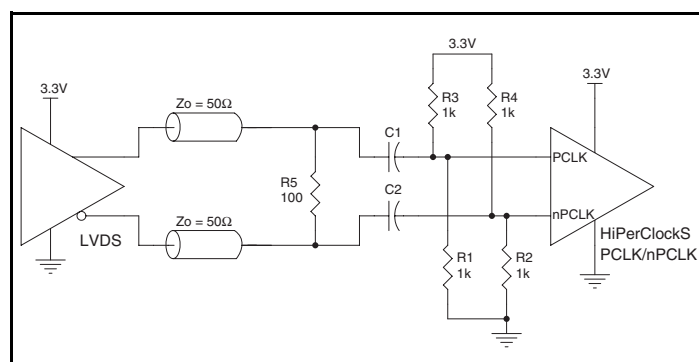
**Figure 2C. HiPerClockS PCLK/nPCLK Input Driven by a 3.3V LVPECL Driver**



**Figure 2D. HiPerClockS PCLK/nPCLK Input Driven by a 3.3V LVPECL Driver with AC Couple**



**Figure 2E. HiPerClockS PCLK/nPCLK Input Driven by an SSTL Driver**



**Figure 2F. HiPerClockS PCLK/nPCLK Input Driven by a 3.3V LVDS Driver**

## Recommendations for Unused Output Pins

### Inputs:

#### PCLK/nPCLK INPUTS

For applications not requiring the use of a differential input, both the PCLK and nPCLK pins can be left floating. Though not required, but for additional protection, a 1k $\Omega$  resistor can be tied from PCLK to ground. For applications

#### LVC MOS Control Pins

All control pins have internal pull-ups or pull-downs; additional resistance is not required but can be added for additional protection. A 1k $\Omega$  resistor can be used.

### Outputs:

#### LVPECL Outputs

All unused LVPECL outputs can be left floating. We recommend that there is no trace attached. Both sides of the differential output pair should either be left floating or terminated.

## Termination for 3.3V LVPECL Outputs

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive 50 $\Omega$

transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 3A and 3B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

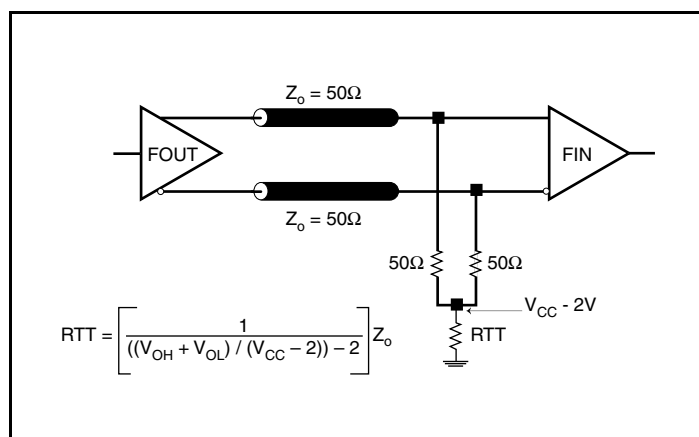


Figure 3A. 3.3V LVPECL Output Termination

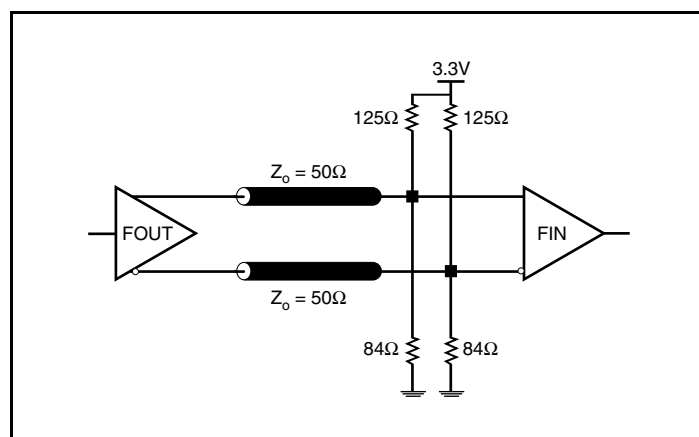
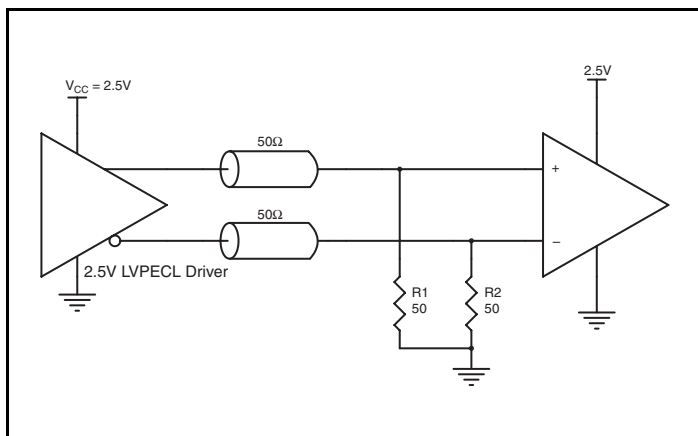


Figure 3B. 3.3V LVPECL Output Termination

Figure 4A and Figure 4B show examples of termination for 2.5V LVPECL driver. These terminations are equivalent to terminating  $50\Omega$  to  $V_{CC} - 2V$ . For  $V_{CC} = 2.5V$ , the  $V_{CC} - 2V$  is very close to

The diagram shows a 2.5V LVPECL driver on the left, represented by a triangle with a non-inverting input connected to  $V_{CC} = 2.5V$  and an inverting input connected to ground. The driver's output is connected to the non-inverting input (+) of a 2.5V LVCMOS receiver on the right. The receiver's inverting input (-) is connected to ground. A feedback network consisting of three resistors,  $R1$  (50),  $R2$  (50), and  $R3$  (18), is connected between the receiver's output and its inverting input. The output of the receiver is connected to  $2.5V$ .

### Figure 4B. 2.5V LVPECL Driver Termination Example



### Figure 4C. 2.5V LVPECL Driver Termination Example

## Termination for 5V LVPECL Outputs

This section shows examples of 5V LVPECL output termination. *Figure 5A* shows standard termination for 5V LVPECL. The termination requires matched load of  $50\Omega$  resistors pull down to

$V_{CC} - 2V = 3V$  at the receiver. *Figure 5B* shows Thevenin equivalence of *Figure 5A*. In actual application where the 3V DC power supply is not available, this approach is normally used.

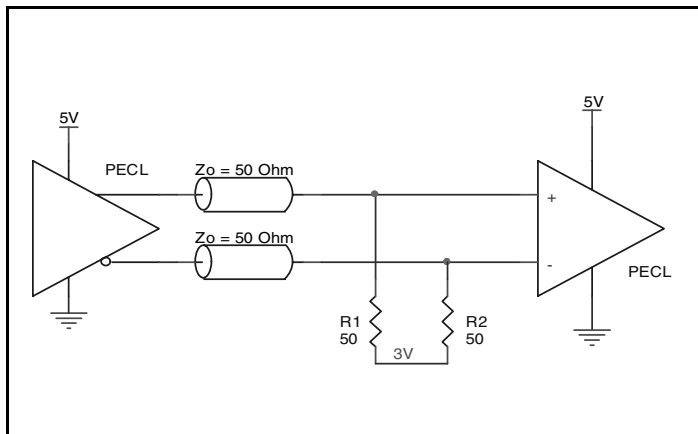


Figure 5A. 5V LVPECL Driver Termination Example

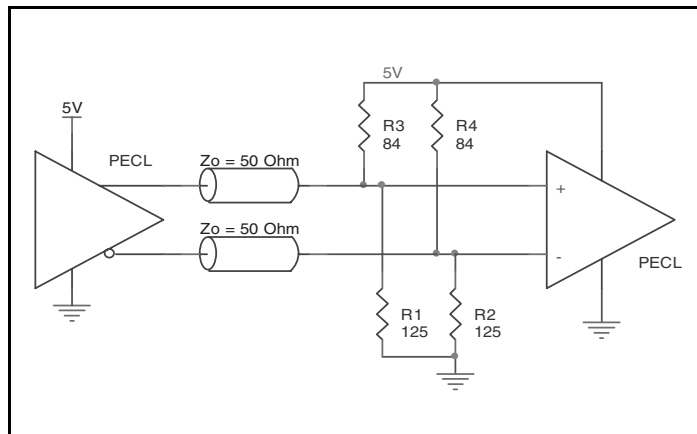


Figure 5B. 5V LVPECL Driver Termination Example

## Power Considerations

This section provides information on power dissipation and junction temperature for the ICS853013. Equations and example calculations are also provided.

### 1. Power Dissipation.

The total power dissipation for the ICS853013 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{CC} = 5.25V$ , which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)<sub>MAX</sub> =  $V_{CC\_MAX} * I_{EE\_MAX} = 5.25V * 60mA = 315mW$
- Power (outputs)<sub>MAX</sub> = **30.94mW/Loaded Output pair**  
If all outputs are loaded, the total power is  $6 * 30.94mW = 185.64mW$

**Total Power**<sub>MAX</sub> (3.8V, with all outputs switching) =  $315mW + 185.64mW = 500.64mW$

### 2. Junction Temperature.

Junction temperature,  $T_j$ , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS devices is 125°C.

The equation for  $T_j$  is as follows:  $T_j = \theta_{JA} * Pd\_total + T_A$

$T_j$  = Junction Temperature

$\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

$Pd\_total$  = Total Device Power Dissipation (example calculation is in section 1 above)

$T_A$  = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming no air flow and a multi-layer board, the appropriate value is 46.2°C/W per Table 6 below.

Therefore,  $T_j$  for an ambient temperature of 85°C with all outputs switching is:

$$85^\circ C + 0.501W * 46.2^\circ C/W = 108.1^\circ C. \text{ This is below the limit of } 125^\circ C.$$

This calculation is only an example.  $T_j$  will obviously vary depending on the number of loaded outputs, supply voltage, air flow and the type of board (single layer or multi-layer).

**Table 6. Thermal Resistance  $\theta_{JA}$  for 20 Lead SOIC Forced Convection**

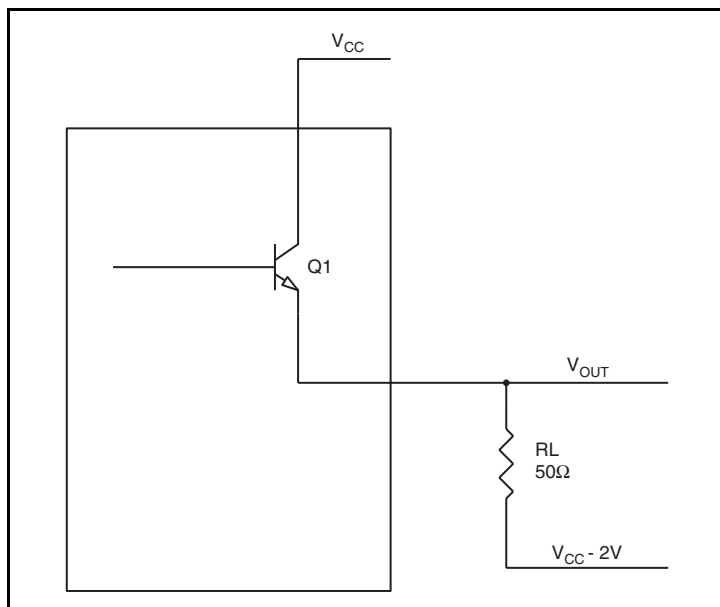
Linear Feet per Minute	$\theta_{JA}$ by Velocity		
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	83.2°C/W	65.7°C/W	57.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	46.2°C/W	39.7°C/W	36.8°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

### 3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in *Figure 6*.



**Figure 6. LVPECL Driver Circuit and Termination**

To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of  $V_{CC} - 2V$ .

- For logic high,  $V_{OUT} = V_{OH\_MAX} = V_{CC\_MAX} - 0.935V$   
 $(V_{CC\_MAX} - V_{OH\_MAX}) = 0.935V$
- For logic low,  $V_{OUT} = V_{OL\_MAX} = V_{CC\_MAX} - 1.67V$   
 $(V_{CC\_MAX} - V_{OL\_MAX}) = 1.67V$

$Pd\_H$  is power dissipation when the output drives high.

$Pd\_L$  is the power dissipation when the output drives low.

$$Pd\_H = [(V_{OH\_MAX} - (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OH\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) = [(2V - 0.935V)/50\Omega] * 0.935V = \mathbf{19.92mW}$$

$$Pd\_L = [(V_{OL\_MAX} - (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OL\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) = [(2V - 1.67V)/50\Omega] * 1.67V = \mathbf{11.02mW}$$

$$\text{Total Power Dissipation per output pair} = Pd\_H + Pd\_L = \mathbf{30.94mW}$$

## Reliability Information

Table 7.  $\theta_{JA}$  vs. Air Flow Table for a 20 Lead SOIC

$\theta_{JA}$ vs. Air Flow			
Linear Feet per Minute	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	83.2°C/W	65.7°C/W	57.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	46.2°C/W	39.7°C/W	36.8°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

## Transistor Count

The transistor count for ICS853013 is: 226

Pin compatible with MC100LVEL13 and MC100EL13

## Package Outline and Package Dimensions

Package Outline - M Suffix for 20 Lead SOIC

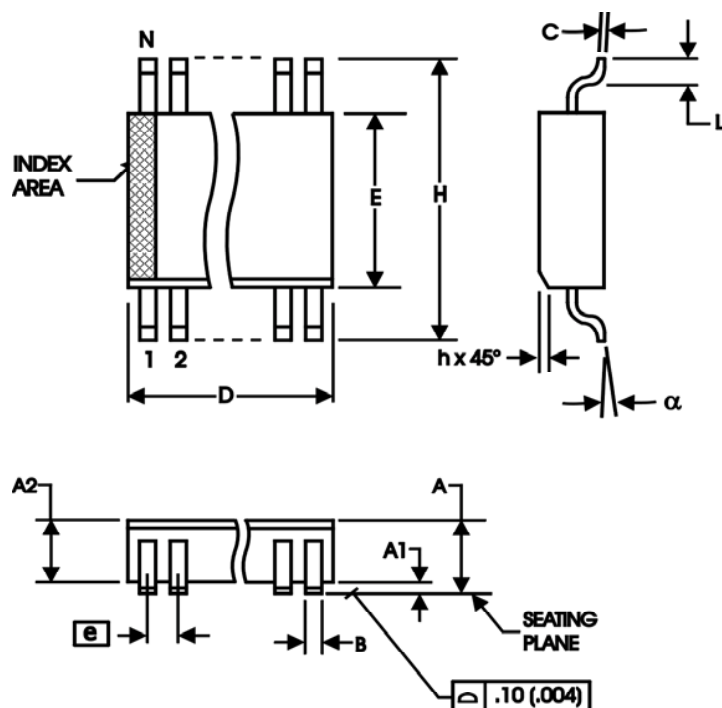


Table 8. Package Dimensions for 20 Lead SOIC

300 Millimeters All Dimensions in Millimeters		
Symbol	Minimum	Maximum
N	20	
A		2.65
A1	0.10	
A2	2.05	2.55
B	0.33	0.51
C	0.18	0.32
D	12.60	13.00
E	7.40	7.60
e	1.27 Basic	
H	10.00	10.65
h	0.25	0.75
L	0.40	1.27
$\alpha$	0°	7°

Reference Document: JEDEC Publication 95, MS-013, MS-119

## Ordering Information

Table 9. Ordering Information

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
853013AM	ICS853013AM	20 Lead SOIC	Tube	-40°C to 85°C
853013AMT	ICS853013AM	20 Lead SOIC	1000 Tape & Reel	-40°C to 85°C
853013AMLF	ICS853013AMLF	"Lead-Free" 20 Lead SOIC	Tube	-40°C to 85°C
853013AMLFT	ICS853013AMLF	"Lead-Free" 20 Lead SOIC	1000 Tape & Reel	-40°C to 85°C

NOTE: Parts that are ordered with an "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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## Revision History Sheet

Rev	Table	Page	Description of Change	Date
A	T8	8 16	Added <i>Recommendations for Unused Input and Output Pins</i> . Ordering Information Table - added Lead-Free marking.	10/19/05
B	T4B T4C T4D T4E	3 4 4 5 9 12 13	3.3V LVPECL DC Characteristics - changed $I_{IH}$ max. from 150 $\mu$ A to 200 $\mu$ A. Changed $I_{IL}$ min. from -150 $\mu$ A to -200 $\mu$ A. 2.5V LVPECL DC Characteristics - changed $I_{IH}$ max. from 150 $\mu$ A to 200 $\mu$ A. Changed $I_{IL}$ min. from -150 $\mu$ A to -200 $\mu$ A. 5V LVPECL DC Characteristics - changed $I_{IH}$ max. from 150 $\mu$ A to 200 $\mu$ A. Changed $I_{IL}$ min. from -150 $\mu$ A to -200 $\mu$ A. ECL DC Characteristics - changed $I_{IH}$ max. from 150 $\mu$ A to 200 $\mu$ A. Changed $I_{IL}$ min. from -150 $\mu$ A to -200 $\mu$ A. Updated <i>LVPECL Clock Input Interface Section</i> . Added <i>Termination for 5V LVPECL Outputs</i> . Power Considerations - updated Junction Temperature equation with worst case thermal resistance of 46.2°C/W.	2/7/08

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